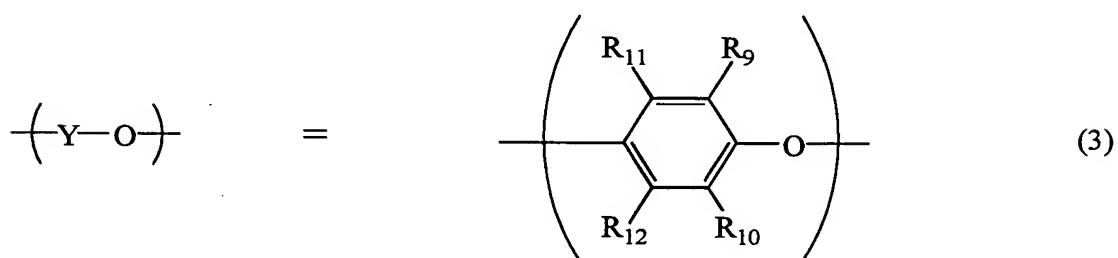
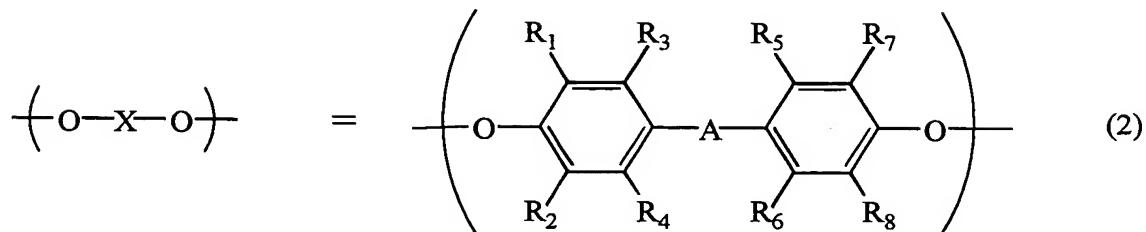
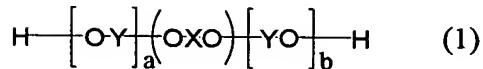


What is claimed is:

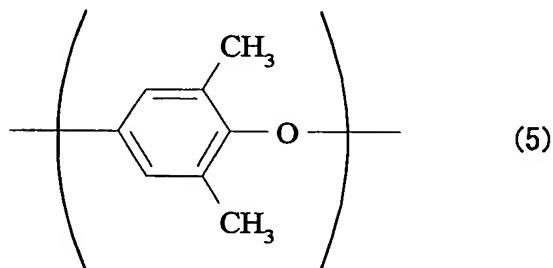
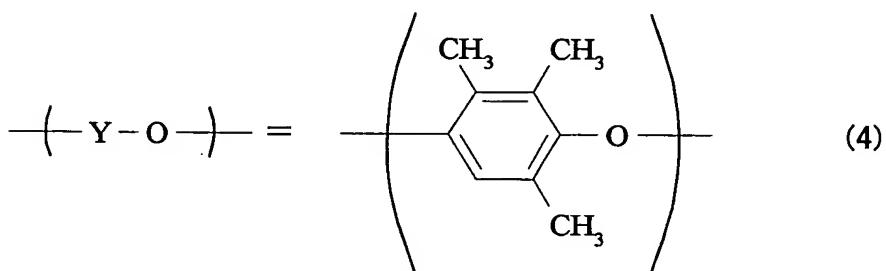
1. An epoxy resin curing agent having a number average molecular weight of 500 to 3,000, represented by the formula  
5 (1),



wherein - (O-X-O) - is represented by the formula (2)  
10 (in which R<sub>1</sub>, R<sub>2</sub>, R<sub>7</sub> and R<sub>8</sub> may be the same or different and are a halogen atom, an alkyl group having 6 or less carbon atoms or a phenyl group, R<sub>3</sub>, R<sub>4</sub>, R<sub>5</sub> and R<sub>6</sub> may be the same or different and are a hydrogen atom, a halogen atom, an alkyl group having 6 or less carbon atoms or a phenyl group, and A is a direct bond or a linear, branched or cyclic hydrocarbon having 20 or less carbon atoms), - (Y-O) - is an arrangement of one kind of structure defined by the formula (3) or a random arrangement of at least two kinds of structures defined by the formula (3)  
15 (in which R<sub>9</sub> and R<sub>10</sub> may be the same or different and are a halogen

atom, an alkyl group having 6 or less carbon atoms or a phenyl group and R<sub>11</sub> and R<sub>12</sub> may be the same or different and are a hydrogen atom, a halogen atom, an alkyl group having 6 or less carbon atoms or a phenyl group), and each of a and b is an integer  
5 of 0 to 30, provided that at least either a or b is not 0.

2. The epoxy resin curing agent according to claim 1,  
wherein R<sub>1</sub>, R<sub>2</sub>, R<sub>7</sub> and R<sub>8</sub> in -(O-X-O)- of the formula  
10 (2) are a methyl group, and -(Y-O)- has a structure of an  
arrangement of the formula (4) or the formula (5) or a random  
arrangement of the formula (4) and the formula (5),



3. The epoxy resin curing agent according to claim 2,  
15 wherein R<sub>3</sub>, R<sub>4</sub>, R<sub>5</sub> and R<sub>6</sub> in -(O-X-O)- of the formula  
(2) are a hydrogen group.

4. The epoxy resin curing agent according to claim 2,  
wherein, in -(O-X-O)- of the formula (2), R<sub>3</sub> and R<sub>6</sub>  
20 are a hydrogen group and R<sub>4</sub> and R<sub>5</sub> are a methyl group.

5. The epoxy resin curing agent according to claim 2,  
wherein -(Y-O)- is represented by the formula (5).
- 5 6. A curable epoxy resin composition containing an epoxy  
resin and the epoxy resin curing agent recited in claim 1.
7. A cured product obtainable by curing the curable epoxy  
resin composition recited in claim 6.

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